



Material Content Data Sheet



Sales Product Name		IPI111N15N3 G		Issued		22. January 2018		
MA#		MA001282308						
Package		PG-TO262-3-1		Weight*		1577.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.752	0.68	0.68	6814	6814
leadframe	inorganic material	phosphorus	7723-14-0	0.255	0.02		162	
	non noble metal	iron	7439-89-6	0.851	0.05		539	
	non noble metal	copper	7440-50-8	849.682	53.85	53.92	538471	539172
	non noble metal	aluminium	7429-90-5	10.198	0.65	0.65	6463	6463
wire	non noble metal	aluminium	7429-90-5	10.198	0.65	0.65	6463	6463
encapsulation	organic material	carbon black	1333-86-4	8.658	0.55		5487	
	plastics	epoxy resin	-	95.234	6.04		60353	
	inorganic material	silicondioxide	60676-86-0	473.282	29.99	36.58	299934	365774
leadfinish	non noble metal	tin	7440-31-5	15.198	0.96	0.96	9631	9631
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.145	0.01		92	
	noble metal	silver	7440-22-4	0.182	0.01		115	
	non noble metal	lead	7439-92-1	6.939	0.44	0.46	4397	4604
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		20	
	non noble metal	iron	7439-89-6	0.106	0.01		67	
	non noble metal	copper	7440-50-8	106.210	6.73	6.74	67309	67396
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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